## **REMARKS**

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page(s) is captioned "Version With Markings To Show Changes Made."

Respectfully submitted,

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## VERSION WITH MARKINGS TO SHOW CHANGES MADE

## IN THE SPECIFICATION

Page 1, before the first line, insert as a separate paragraph:

This application is the US national phase of international application PCT/GB00/02571 filed 05 July 2000, which designated the US.

## IN THE CLAIMS

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- A method according to claim 1, 2 or 3 wherein the printed circuit conductor 4. pattern includes conductor regions less than about 30 microns wide.
- A method according to claim 1, 2, 3 or 4 wherein the printed circuit 5. conductor pattern includes conductor regions spaced by less than about 30 microns.
- A method according to any one of the preceding claims 1 wherein the etch 6. band is less than about 30 microns wide.
- A mask for use in producing a resist pattern for etching of a printed circuit, 7. the mask being produced by the method of any one of the preceding claims 1.
- A printed circuit according to claim 8 or 9 wherein the etch band is of 10. substantially the same width as the narrowest conductor or the narrowest separation between conductors in the printed circuit

- 11. A printed circuit according to claim 8, 9 or 10 wherein the printed circuit conductor pattern includes conductor regions less than about 30 microns wide.
- 12. A printed circuit according to claim 8,9, 10 or 11 wherein the printed circuit conductor pattern includes conductor regions spaced by less than about 30 microns.
- 13. A printed circuit according to any one of claims 8 to 12 wherein the etch band is less than 30 microns wide.
- 16. A method according to claim 14 or 15-wherein the pattern includes conductor elements spaced by less than about 30 microns.
- 17. A method according to claim 14, 15 or 16 wherein the regions of constant width are of substantially the same width as the narrowest element or narrowest separation between elements in the printed circuit.
- 18. A mask or a printed circuit substantially as hereinbefore described with reference to and as illustrated in figures 1 and 3 of the accompanying drawings.
- 19. A method of producing a mask or a printed circuit substantially as hereinbefore described.